IPC ASSOCIATION CONNI ELECTRONICS INDUS	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfg Information				
upplier Info	ormation													
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
nsemi										2022-02-11				
Contact Name		Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-Env-St	tewards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized Rep	oresentative*	Title - Representative			P	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requ	uester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	rsion Manufacturing Site		V	/eight*	UOM	Unit Type
		NVB25P06T4G PFET D2PAK 60°		PFET D2PAK 60V	27.5A 82MO		2022-02-11	2-02-11 MY1		1.	420.1	mg	Each	
	ing Proccess Informa													·
			Terminal Base Alloy J-STD-020 MSL		Rating	Peak Process Body Temperate		T *		Temperatu	re Numb	er of Reflow Cyc	cles	
Matte	e Tin (Sn) - annealed	C	CU Alloy	1			260		C	30	second	s 3		
omments														
vel 1 - maximu	um time at peak temperat	ure during sol	dering is 10-	30 seconds										
or more inform	nation regarding material	composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall applier be a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.34	mg	A	Lead (Pb)	7439-92-1	7a	10.773	mg
			Supplier	Tin (Sn)	7440-31-5		0.567	mg
Lead Frame	851.91	mg	В	Nickel (Ni)	7440-02-0		2.5557	mg
			Supplier	Copper (Cu)	7440-50-8		849.3542	mg
Mold Compound-Black	529.31	mg		Phenolic Resin	proprietary data		42.3448	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		42.3448	mg
			Supplier	Carbon Black (C)	1333-86-4		2.6465	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		441.9738	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Al	0.2	mg	Supplier	Aluminum (Al)	7429-90-5		0.2	mg